LINQSOL **EMC-7535** Black epoxy molding compound



- Green molding compound
- Designed for high-power devices
- High T_g, low water absorption, low modulus, and excellent thermal stability

LINQSOL EMC-7535 is a green epoxy molding compound specifically developed for high-voltage and high-power semiconductor devices. It offers low modulus to meeting low-stress requirements. With a high glass transition temperature (Tg = 175 °C), minimal moisture absorption, a high comparative tracking index (CTI = 600 V), and a UL 94 V-0 flammability rating, EMC-7535 guarantees strong performance and outstanding reliability. Overall, **LINQSOL EMC-7535** seamlessly integrates advanced material properties, safety compliance, and superior performance, precisely meeting the stringent demands of high-power semiconductor applications.

Cured properties

Property	Value	Unit
General Properties		
Color	Black	-
Filler cut size	75	μm
Specific gravity	1.96	-
Spiral flow at 175 °C	86	cm
Chemical Properties		
Ion content Chloride (Cl ⁻) concentration Sodium (Na ⁺) concentration	≤15 ≤15	ppm ppm
Moisture absorption (PCT, 24 hours)	0.25	%
pH of extract	5-7	-
Electrical conductivity of extract	18	µS · cm ^{−1}
Mechanical Properties		
Flexural strength	156	MPa
Flexural modulus	17	GPa
Electrical Properties		
Volume resistivity at 21 °C, 500 V at 150 °C, 500 V	1.6 × 10 ¹⁶ 9.0 × 10 ¹¹	Ω∙cm Ω∙cm
Comparative tracking index	600	V
Dielectric constant at 21 °C and 1 MHz	3.8	

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Thermal Properties		
Glass transition temperature	175	°C
Coefficient of thermal expansion, $\alpha 1$	13	ppm/K
Coefficient of thermal expansion, $\alpha 2$	37	ppm/K
Gel time at 175 °C	24	S
UL-94 rating	V-0	-

The technical data presented above is intended for reference purposes only. Actual performance may vary based on specific applications and conditions. Users are advised to conduct their own testing and evaluation to ensure compatibility with their specific requirements.

Recommended mold parameters

Parameter	Value	Unit
Molding temperature	170–180	°C
Transfer pressure	40-90	kg/cm ³
Transfer time	10-25	sec
Cure time at 175 °C	1.5-2	min
Post mold cure time at 175 °C	4-6	h

To achieve the best results, test the recommended conditions on the mold. Users should conduct their own testing to ensure it meets their specific needs and application.

Processing Instructions

- Before use, let **LINQSOL EMC-7535** reach room temperature for 24 hours. Keep the bag unopened and stored in a dry location with a relative humidity of ≤50% during thawing to prevent moisture contamination.
- Use the materials within 72 hours after removing the container from cold storage.

Storage and Handling

LINQSOL EMC-7535 is available in pressed pellets in a wide range of sizes to meet specific customer needs. To ensure product integrity, keep it away from oxidizing materials. For long-term storage, maintain a cold environment. The shelf life at 5 °C is 183 days.

Please note that the provided information is based on available data and typical conditions. For specific applications and detailed test results, refer to the actual test data and conduct appropriate certifications.

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